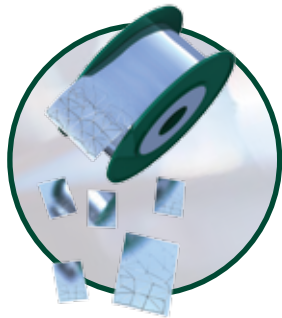
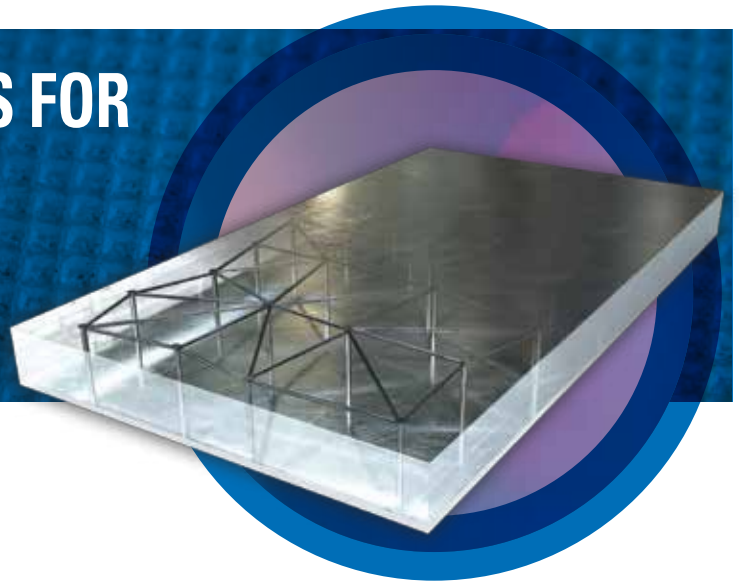
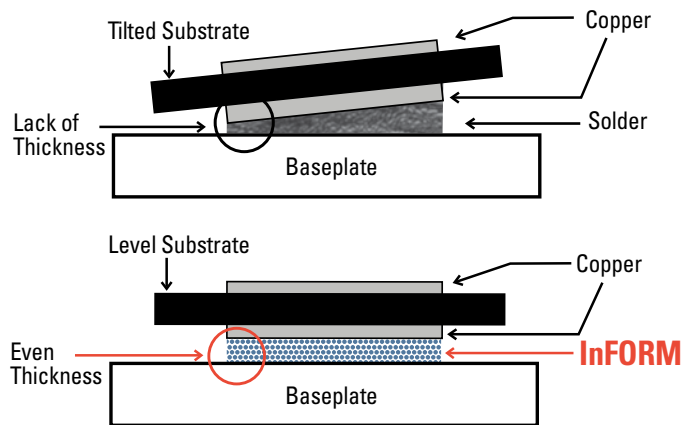


HIGH-RELIABILITY SOLDERS FOR MECHANICAL APPLICATIONS



InFORMS[®] Ribbon

- Patent pending
- Drop-in replacement for bondline control
- Increases reliability
- Ideal for automated assembly



LV1000 Flux-Coated Preforms

- Low-voiding
- Halide-free; meets ROL0 requirements
- Uniform and level coating
- Durable for pick-and-place equipment
- Passes Telecordia (Bellcore) testing in activated and unactivated states



Typical Poor Voiding
10-12% Void Area



LV1000
<2% Void Area

Contact our experts today: esolders@indium.com

Learn more: www.indium.com/ESM

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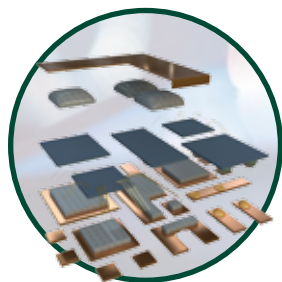
HIGH-RELIABILITY SOLDERS FOR MECHANICAL APPLICATIONS



Solder Fortification® Preforms

- Increased solder volume
- Improved drop test results
- Fewer issues with flux residue
- Reduced rework
- Improved fillet shape and volume

| Name | Size | Quantity Per Reel | | Example Weight: SAC305 (grams/ea) |
|------|--|-------------------|-----|-----------------------------------|
| | | 7" | 13" | |
| 0201 | .010" x .020" x .010" rectangle (0.254mm x 0.508mm x 0.254mm) | 1k | 50k | 0.00024 |
| 0402 | .020" x .040" x .019" rectangle (0.508mm x 1.01mm x 0.48mm) | 1k | 15k | 0.00182 |
| 0603 | .030" x .060" x .030" rectangle (0.76mm x 1.52mm x 0.787mm) | 1k | 15k | 0.00672 |
| 0805 | .050" x .080" x .050" rectangle (1.27mm x 2.03mm x 1.27mm) | 1k | 15k | 0.02410 |



BiAgX® Solder Paste

- Drop-in replacement for high-Pb solder paste
- Pb-free and Sb-free
- High-melting (>260°C) solder joint
- Low-voiding
- Available in both dispense and printing forms

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